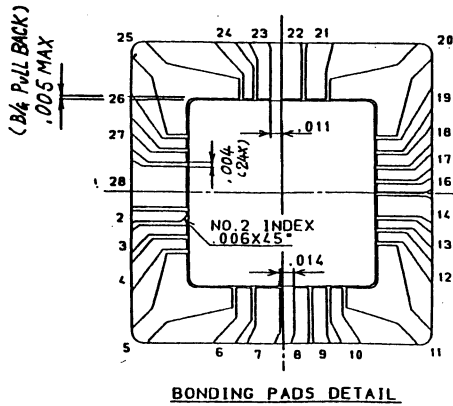
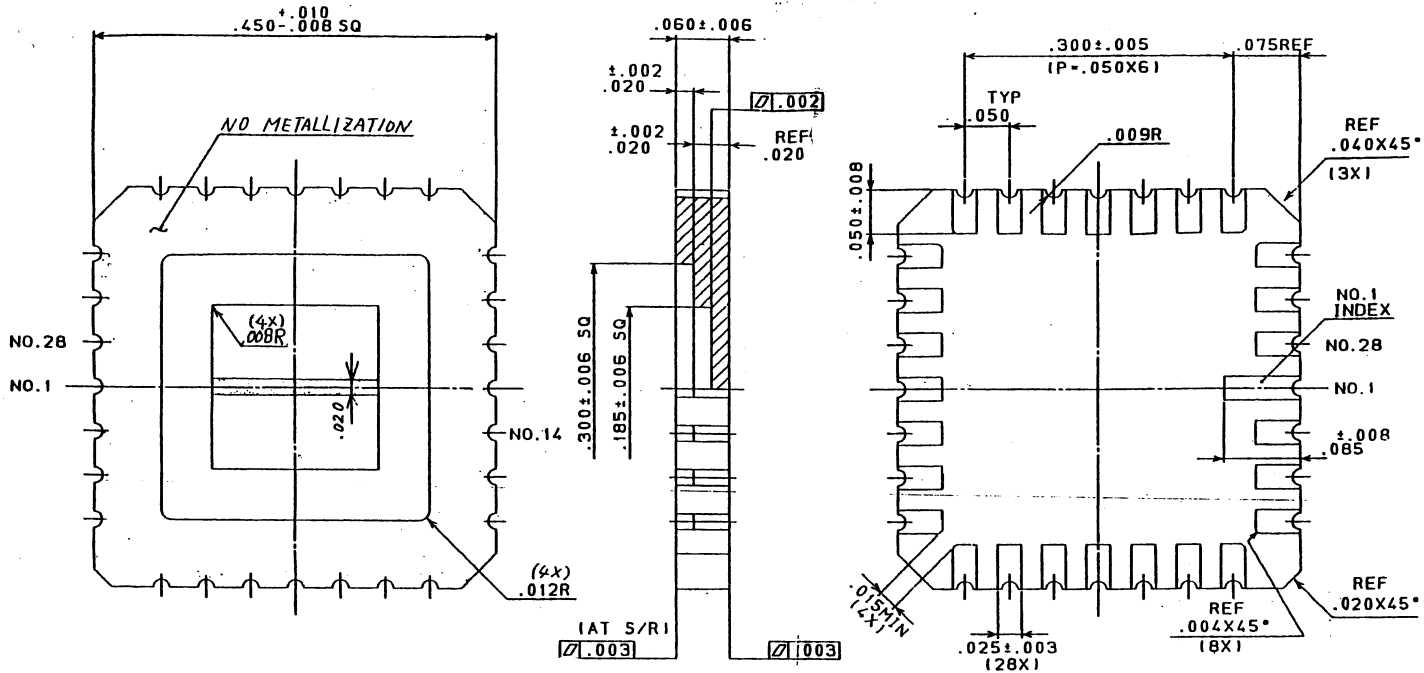


# SSM P/N LCC02843



B/4 PAD WIDTH	B/4 PAD NO.
.008	13, 16
.009	3, 12
.010	2, 4, 17, 24, 26, 27
.011	18, 19
.012	10
.013	23
.014	8, 9
.015	6
.020	14, 21, 22
.024	7
.040	28

- NOTES:
1. PLATING: NICKEL (180μ MINI PLUS GOLD (100μ MINI).
  2. PAD NO. 14 SHALL BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD.
  3. RESISTANCE: 200 mΩ MAX
  4. OPEN CASTELLATION: NO. 1, 15.

Item	Name	Material	Description	Rev.	Description	Date
	CERAMIC	BLACK ALUMINA			NEW DRAWING	OCT. - 5 - 1992
	UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 4% N. L. T. 2 DECIMALS .XX ± .01 3 DECIMALS .XXX ± .005					
	DRAWN <i>A. Chapal</i>					
	CHECKED					
	APPROVED <i>J.W.</i>				TITLE	
	CUSTOMER				28LD CHIP CARRIER	
DWG NO.	70-0215-03	UNIT	INCH	DWG NO.	IRK 28FO-5245D	SIZE
		SCALE	8/1			A-31